

CLAIMS

What is claimed is:

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1. An testing apparatus for a wafer of semiconductor dice comprising:
a first rigid support member for receiving a plurality of semiconductor dice in wafer form having a predetermined orientation, the first rigid support member having a plurality of contact members thereon and having a plurality of electrical connectors connected to the contact members for establishing communication with test circuitry;
a second rigid support member for selectively engaging the first rigid support member to retain the plurality of semiconductor dice in wafer form therebetween, one of the first rigid support member and the second rigid support member including a single cavity for retaining said wafer therein during testing; and
a single biasing assembly including a single floating platform of a preselected area substantially sized for said single cavity, the single biasing assembly mounted to one of the first rigid support member and second rigid support member, the single biasing assembly sized for uniformly biasing said wafer form against the contact members.

2. The apparatus as claimed in claim 1, wherein the plurality of semiconductor dice comprises a wafer.

3. The apparatus as claimed in claim 1, wherein the plurality of semiconductor dice comprises a die cluster in wafer form.

4. The apparatus as claimed in claim 1, wherein the single biasing assembly comprises the single floating platform in contact with an elastomeric polymer member.

5. The apparatus as claimed in claim 1, further comprising aligning devices for aligning the first rigid support member with the second rigid support member.

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6. A wafer testing apparatus comprising:
a first rigid support member and a second rigid support member for receiving a wafer
therebetween, one of the first rigid support member and second rigid support member
including a single cavity for retaining the wafer therein during testing;
a plurality of contact members formed on the first rigid support member for communicating with
electrical connectors for connecting to external test circuitry;
a single biasing assembly including a single floating platform having a preselected area
substantially sized to correspond with said single cavity and an elastomeric member
disposed on the second rigid support member, the single biasing assembly sized for
uniformly biasing the wafer towards the contact members, the single floating platform
directly supporting the wafer having the elastomeric member sandwiched between the
single floating platform and the second rigid support member.

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7. The apparatus as claimed in claim 6, further comprising an alignment device for
aligning the first rigid support member and the second rigid support member with one another.

8. The apparatus claimed in claim 6, further comprising an alignment device
including a dowel on one of the first rigid support member and second rigid support member and
a corresponding opening on the other of the first rigid support member and the second support
member.